

UPB652A - PRELIMINARY

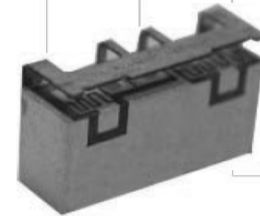
5.925-7.125 GHz UPB Series Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications



Part Dimensions: 9.0 × 4.0 × 3.1 mm • 0.4 g
Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared other bandpass filter technologies.

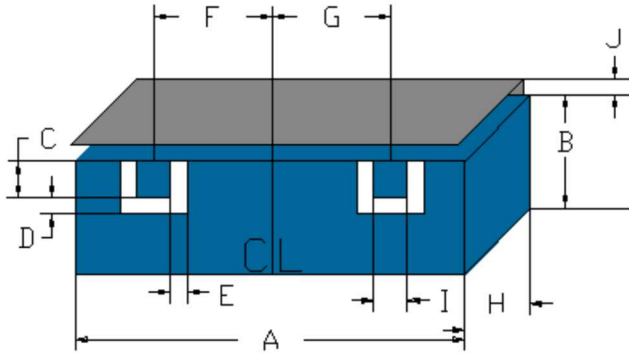
Electrical Specifications

| Parameter | Frequency (MHz) | Typical at 25°C | Spec. at 25°C | Spec. over -40°C to +85°C |
|--------------------------------------|-----------------|-----------------|---------------|---------------------------|
| Nominal Impedance | - | 50 ohms | - | - |
| Average Input Power | - | - | - | 2.0 Watt max |
| Peak Input Power | - | - | - | 20 Watt max |
| Input-Output Response | | | | |
| Passband Insertion Loss (20 MHz avg) | 5925-7125 | | | 1.5 dB max |
| Passband Return Loss | 5925-7125 | | | 10-12 dB min |
| Attenuation: | 1-5000 | | | 40 dB min |
| | 5150-5350 | | | 28-30 dB min |
| | 5351-5750 | | | 18-20 dB min |
| | 7800-9999 | | | 20 dB min |

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

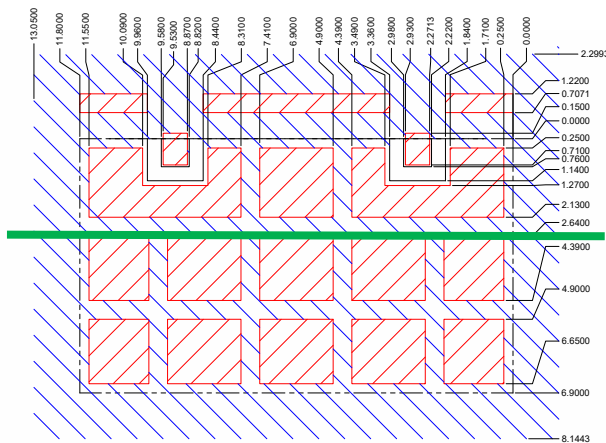
| Specification Allowance | |
|-------------------------|--------|
| Insertion Loss | 0.1 dB |
| Return Loss | 1.0 dB |
| Attenuation | 1.0 dB |

Mechanical Drawing



| Dim. | Nominal (mm) | Tolerance (±mm or Max) |
|------|-----------------|---------------------------|
| A | 8.97 | max |
| B | <3.00 | max |
| C | 0.76 | 0.13 |
| D | 0.38 | 0.13 |
| E | 0.38 | 0.13 |
| F | 3.30 | 0.13 |
| G | 3.30 | 0.13 |
| H | 3.10 | max |
| I | 0.76 | 0.13 |
| J | 1.00 | max |

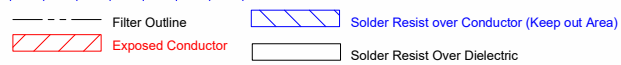
PCB Layout



IMPORTANT: Please assure ≥ 30 mils (0.75mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the required ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

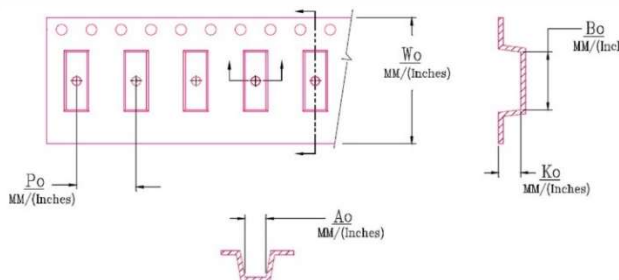
Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.



Packaging and Marking

| Dimension | Units | Spec. | Product Marking |
|---------------|-------|-------|-----------------|
| Reel Diameter | mm | 330 | CTS |
| Reel Weight | kg | 5.5 | 652 |
| Reel Quantity | ea. | 500 | YWW |

Customer Feed Direction → → →



| W_0 | A_0 | B_0 | K_0 | P_0 |
|---------------------|---------------------|---------------------|---------------------|--------------------|
| 0.945 in 24.0 mm | 0.177 in 4.50 mm | 0.366 in 9.30 mm | 0.132 in 3.35 mm | 0.315 in 8.0 mm |

Electrical Response

